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MCGEP0178USA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of		
George S. Bokisa et al.	Art Unit:	2827
Serial No: 10/002,714	Examiner:	I.B. Patel
Filed: November 1, 2001		

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TECHNOLOGY CENTER 2800

For: A TIN WHISKER-FREE PRINTED CIRCUIT BOARD

REPLY TO OFFICE ACTION MAILED DECEMBER 19, 2002

VIA FACSIMILE
NON-FEE AMENDMENT
Commissioner for Patents
Washington, D.C. 20231

Sir:

This Reply is filed as a complete response to the Office Action dated December 19, 2002, which provided a three-month time for reply. Accordingly, Applicants' Reply is timely filed. Entry of the present Reply and reconsideration of the application based on the present Reply are respectfully requested.

Docket No. MCGEP0178USA Serial No. 10/002,714

AMENDMENT

In the Specification:

At page 6, between original lines 10 and 11, please insert the following:

Brief Description of the Drawing

Fig. 1 is a schematic, cross-sectional view of a substrate including electrical circuitry, a coating of tin and an alloy cap layer on the tin coating, in accordance with an embodiment of the present invention.

It should be appreciated that for simplicity and clarity of illustration, elements shown in the Figure have not necessarily been drawn to scale. For example, the dimensions of some of the elements may be exaggerated relative to each other for clarity.

At page 6, between original lines 11 and 12, please insert the following:

Fig. 1 is a schematic, cross-sectional view of a device 10, such as a printed circuit board, in accordance with an embodiment of the present invention. The device 10 includes a substrate 12, on which is formed electrical circuitry 14. The device 10 further includes a tin coating 16 formed on the electrical circuitry 14. An alloy cap layer 18 is formed on the tin coating 16, in which the alloy cap layer 18 includes at least two immersion-platable metals.